

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

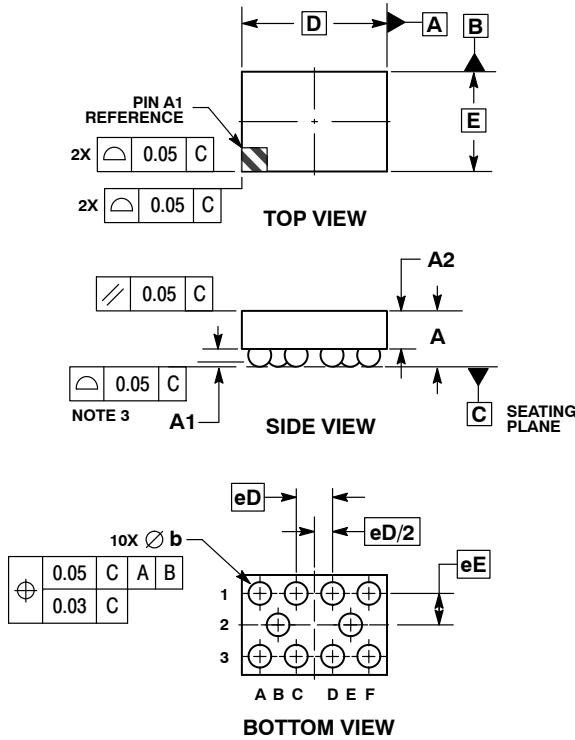
ON Semiconductor®



SCALE 4:1

**WLCSP10, 1.60x1.10**  
CASE 567DE-01  
ISSUE O

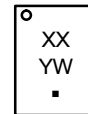
DATE 10 MAY 2011



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.57	0.63
A1	0.17	0.24
A2	0.41	REF
b	0.24	0.29
D	1.60	BSC
E	1.10	BSC
eD	0.400	BSC
eE	0.347	BSC

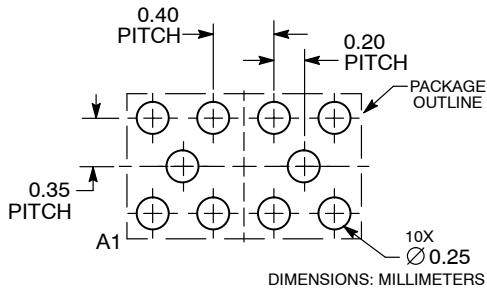
### GENERIC MARKING DIAGRAM\*



- Y = Year
- W = Work Week
- = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

### RECOMMENDED SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>DESCRIPTION:</b>	<b>WLCSP10, 1.60X1.10</b>	<b>PAGE 1 OF 1</b>

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